Attorney's Docket No. 02986.P028 PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kenneth S. McElvain

Application No.: 10/626,031

Filing Date: July 23, 2003

For: Integrated Circuit Devices and Methods and Apparatuses for Designing Integrated Circuit Devices

Examiner: Not Yet Assigned
Art Unit: Not Yet Assigned

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Sir:

Enclosed is a copy of Information Disclosure Citation Form PTO-1449 together with copies of the documents cited on that form. It is respectfully requested that the cited documents be considered and that the enclosed copy of Information Disclosure Citation Form PTO-1449 be initialed by the Examiner to indicate such consideration and a copy thereof returned to applicant(s).

Pursuant to 37 C.F.R. § 1.97, the submission of this Information Disclosure Statement is not to be construed as a representation that a search has been made and is not to be construed as an admission that the information cited in this statement is material to patentability.

Pursuant to 37 C.F.R. § 1.97, this Information Disclosure Statement is being submitted under one of the following (as indicated by an "X" to the left of the appropriate paragraph):

__X__ 37 C.F.R. §1.97(b).

_____ 37 C.F.R. §1.97(c). If so, then enclosed with this Information Disclosure Statement is one of the following:

____ A statement pursuant to 37 C.F.R. §1.97(e); or

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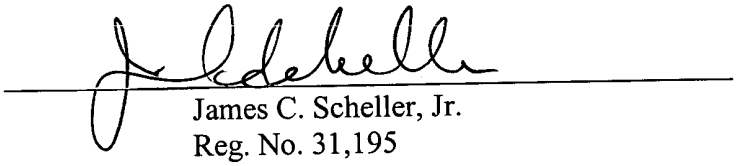
If there are any additional charges, please charge Deposit Account No. 02-2666.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: 8/12, 2003



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Substitute for Form 1449A/PTO (Modified) (use as many sheets as necessary)	Attorney Docket No.: 02986.P028	Application Number: 10/626,031
	First Named Inventor: Kenneth S. McElvain	
	Filing Date: July 23, 2003	

U.S. PATENT DOCUMENTS

Exam. Initial*	Cite No.[1]	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number	Kind Code[2] (If known)			

OTHER ART – NO PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No[1]	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	Translation[2]
		Magma Design Automation, Inc., "Deep-Submicron Signal Integrity", white paper, 2002	
		Andrey V. Mezhiba, Eby G. Friedman, "Scaling Trands of On-Chip Power Distribution Noise", SLIP'02, April 6-7, 2002, San Diego, California, USA, pp.47-53	
		Sani R. Nassif, Onsi Fakhouri, "Technology Trends in Power-Grid-Induced Noise", SLIP'02, April 6-7, 2002, San Diego, California, USA, pp.55-59	
		Seongkyun Shin, Yungseon Eo, William R. Eisenstadt, Jongin Shim, "Analytical Signal Integrity Verification Models for Inductance-Dominant Multi-Coupled VLSI Interconnects", SLIP'02, April 6-7, 2002, San Diego, California, USA, pp.61-68	
		S. Khatri, A. Mehrotra, R. Brayton, A. Sangiovanni-Vincentelli, and R. Otten, "A novel VLSI layout fabric for deep sub-micron applications," in *Proceedings of the Design Automation Conference*, (New Orleans), June 1999.	
		Sunil P. Khatri, Robert K. Brayton, Alberto Sangiovanni-Vincentelli, "Cross-talk Immune VLSI Design using a Network of PLAs Embedded in a Regular Layout Fabric", IEEE/ACM International Conference on Computer Aided Design, ICCAD-2000, November 5-9, 2000, San Jose, CA, USA	

Examiner Signature		Date Considered	

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[1]Unique citation designation number. [2]Applicant is to place a check mark here if English language Translation is attached.

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